

Type	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS 2	"20040158409"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:36	
2	BRS 5	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anoma1\$3) with troubleshoot\$3 and micro- fabrication	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 13:58	
3	BRS 1324	700/117,118,183,185.cc1s.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/18 17:16	
4	BRS 1296	700/121.cc1s.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:40	
5	BRS 440	714/46.cc1s.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:41	
6	BRS 6	"6635872"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 14:47	

Type	Hits	Search Text	DBS	Time Stamp	Comments
7	IS&R 2	("5656811").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:43	
8	BRS 82	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3) with troubleshoot\$3 and (micro-fabrication or semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 13:58	
9	IS&R 2	("5938424").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:54	

Type	Hits	Search Text	DBS	Time Stamp	Comments
10	BRS 82	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomals\$3 or trouble\$1) with troubleshoot\$3 and (micro-fabrication or fabrication) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:53	
11	BRS 2	"20030120436"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 13:58	
12	BRS 8391	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomals\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:01	

Type	Hits	Search Text	DBs	Time Stamp	Comments
13	60	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charged with beam\$1 and software	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:02	
14	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charged with beam\$1 and software with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:03	

Type	Hits	Search Text	DBS	Time Stamp	Comments
15	7	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with beam\$1 and software with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:03	
16	21	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with beam\$1 and (program\$4 or software\$1) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:30	

Type	Hits	Search Text	DBS	Time Stamp	Comments
17	15	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1 or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (program\$4 or software\$1) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:04	

Type	Hits	Search Text	DBS	Time Stamp	Comments
18	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1 or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (program\$4 or software\$1 or cod\$3) with execut\$3 and user\$1 with interface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:47	

Type	Hits	Search Text	DBS	Time Stamp	Comments
19	1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunctions\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (tow or dual) with charg\$3 with beam\$1 and (program\$4 or software\$1) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:33	
20	3	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunctions\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (tow or dual) with charg\$3 with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:33	

Type	Hits	Search Text	DBS	Time Stamp	Comments
21	IS&R 2	("6635872") . PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 14:47	
22	BRS 0	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with troubleshoot\$3 and (micro-fabrication or fabrication) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and high with resolution with image\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:54	

Type	Hits	Search Text	DBS	Time Stamp	Comments
23	BRS 2	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomals\$3 or trouble\$1) with troubleshoot\$3 and (micro-fabrication or fabrication) with (semiconductors\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and high with resolution with imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:56	
24	BRS 1173	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomals\$3 or trouble\$1) with (semiconductors\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (micro-fabrication or fabrication) and high with resolution with imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:56	

Type	Hits	Search Text	DBS	Time Stamp	Comments
25	BRS 184	(troubleshoot\$3 or inspect\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (micro-fabrication or fabrication) and high with resolution with imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:57	

Type	Hits	Search Text	DBS	Time Stamp	Comments
26	BRS 70	(troubleshoot\$3 or inspect\$3) with (defect\$1 or errors\$1 or malfunction\$2 or problem\$1 or faults\$1 or fail\$3 or anomalies\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1 or chip\$1 or die\$1) and (micro-fabrication or fabrication) and high with resolution with imag\$3 and defects\$1 with (file\$1 or database)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:58	

Type	Hits	Search Text	DBS	Time Stamp	Comments
27	1	(troubleshoot\$3 or inspect\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (micro-fabrication or fabrication) and high with resolution with imag\$3 and initial\$2 with defect\$1 with (file\$1 dor database) (analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and chemical\$2 with analy\$4 with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:58	
28	107		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:32	

Type	Hits	Search Text	DBS	Time Stamp	Comments
29	BRS 4	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and chemical\$2 with analy\$4 with exposed with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:34	
30	BRS 11	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and chemical\$2 with analy\$4 with expos\$3 with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:38	

Type	Hits	Search Text	DBS	Time Stamp	Comments
31	7	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or troubles\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and EDS with tool\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:41	
32	1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or troubles\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and cross with section\$2 with three with dimension and EDS with tool\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:41	

Type	Hits	Search Text	DBs	Time Stamp	Comments
33	BRS 1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and cross with section\$2 with dimension and EDS with tool\$1	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:42	
34	BRS 1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (cross-section\$2 or (cross with section\$2)) with dimension and EDS	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:42	

Type	Hits	Search Text	DBs	Time Stamp	Comments
35	1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (cross-section\$2 or (cross with section\$2) or (cross with sections\$2)) with (3-d mor dimension\$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:43	
36	142	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (cross-section\$2 or (cross with section\$2) or (cross with sections\$2)) with (3-d mor dimension\$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:06	

Type	Hits	Search Text	DBs	Time Stamp	Comments
37	1	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalies\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and (cross-section\$2 or (cross with sections\$2)) with (3-d mor dimensions\$1) with EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:43	
38	3	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalies\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and (cross-section\$2 or (cross with sections\$2)) with (3-d mor dimensions\$1) same EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:45	

Type	Hits	Search Text	DBS	Time Stamp	Comments
39	BRS 3	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and cut\$4 with (cross-section\$2 or (cross-section\$2) with (3-d or dimension\$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:53	
40	BRS 3	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and cut\$4 with (cross-section\$2 or (cross-section\$2) with (3-d or dimension\$1 or three-dimensional\$2). and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 16:21	

Type	Hits	Search Text	DBs	Time Stamp	Comments
41	BRS 307	(defect\$1 or errors\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalies\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and chemical\$2 with analy\$4 with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:29	
42	BRS 46	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalies\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and chemical\$2 with analy\$4 with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:30	

Type	Hits	Search Text	DBs	Time Stamp	Comments
43	BRS 4	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomals\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) with chemical\$2 with analy\$4 with expos\$3 with surfaces\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:32	
44	BRS 4	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomals\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) with chemical\$2 adj analy\$4 with surfaces\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:32	

Type	Hits	Search Text	DBS	Time Stamp	Comments
45	BRS 3	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1 or chip\$1 or die\$1) and two with charg\$3 with particle\$1 with beam\$1 and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:49	

Type	Hits	Search Text	DBs	Time Stamp	Comments
46	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1 or chip\$1 or die\$1) and charg\$3 with particle\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:18	

Type	Hits	Search Text	DBs	Time Stamp	Comments
47	BRS 2	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1 or chip\$1 or die\$1) same charg\$3 with particle\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:22	

Type	Hits	Search Text	DBS	Time Stamp	Comments
48	BRS 711	(analy\$4 or diagnos\$3) with (defect\$1 or errors\$1 or malfunctions\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 devices with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:04	

Type	Hits	Search Text	DBs	Time Stamp	Comments
49	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1 or chip\$1 or die\$1) and charg\$3 with particle\$1 with device\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:27	

Type	Hits	Search Text	DBS	Time Stamp	Comments
50	2	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (dual or two) with charg\$3 with particle\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:43	
51	2	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (dual or two) with charg\$3 with particle\$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:44	

Type	Hits	Search Text	DBs	Time Stamp	Comments
52	BRS 12	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunctions\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (dual or two) with charg\$3 with particle\$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:45	
53	BRS 0	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and dual with charg\$3, with particle\$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:45	

Type	Hits	Search Text	DBs	Time Stamp	Comments
54	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and dual with charg\$3 with particle\$1 with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:46	
55	6	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and dual same charg\$3 with particle\$1 with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:50	

Type	Hits	Search Text	DBs	Time Stamp	Comments
56	BRS 2	jp-11213935-\$ . did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/15 09:48	
57	BRS 45	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (two or dual) with charg\$3 with particle\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:56	

Type	Hits	Search Text	DBS	Time Stamp	Comments
		(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (two or dual) adj beams and charg\$3 with particle\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:00	
58	BRS 12	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:06	
59	BRS 5				

Type	Hits	Search Text	DBS	Time Stamp	Comments
60	BRS 1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunctions\$2 or problems\$1 or fault\$1 or fails\$3 or anomals\$3 or trouble\$1) with (semiconductors\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3 and user\$1 with (interface or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:07	

Type	Hits	Search Text	DBs	Time Stamp	Comments
61	BRS 5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$ and (program\$4 or software\$1 or cod\$3) with execut\$3 and user\$1 with (interface or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:15	

Type	Hits	Search Text	DBS	Time Stamp	Comments
62	58	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:16	
63	16	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beams and user\$1 with (interface or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:17	

Type	Hits	Search Text	DBs	Time Stamp	Comments
64	BRS 18	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1 or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (two or dual) with beam\$1 and user\$1 with (interface or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:20	

Type	Hits	Search Text	DBS	Time Stamp	Comments
65	BRS 16	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunctions\$2 or problems\$1 or fault\$1 or fails\$3 or anomals\$3 or trouble\$1) with (semiconductors\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1 or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (two or dual) adj beam\$1 and user\$1 with (interface or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:25	

Type	Hits	Search Text	DBS	Time Stamp	Comments
66	0	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunctions\$2 or problem\$1 or fault\$1 or fails\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (two or dual) adj beam\$1 and user\$1 with (interface or communicat\$3) and computer with job\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:26	

Type	Hits	Search Text	DBs	Time Stamp	Comments
67	BRS 16	(analy\$4 or diagnos\$3). with (defect\$1 or error\$1 or malfunctions\$2 or problem\$1 or fault\$1 or fails\$3 or anomals\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1 or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (two or dual) adj beam\$1 and user\$1 with (interface or communicat\$3) and computer	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:26	

Type	Hits	Search Text	DBs	Time Stamp	Comments
68	BRS 16	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunctions\$2 or problems\$1 or fault\$1 or fails\$3 or anomalies\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (two or dual) adj beam\$1 and user\$1 with (interface or communicat\$3) with computer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 16:12	

Type	Hits	Search Text	DBs	Time Stamp	Comments
69	BRS 1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunctions\$2 or problems\$1 or fault\$1 or fails\$3 or anomalies\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1 or chip\$1 or die\$1) and charge\$3 with particle\$1 with beam\$1 and (two or dual) adj beam\$1 and user\$1 with (interface or communicat\$3) with computer and receiv\$3 with request\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:34	

Type	Hits	Search Text	DBS	Time Stamp	Comments
70	BRS 44	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunctions\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and ion with mill\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 16:45	
71	ISS&R 2	("6539106").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 17:02	

Type	Hits	Search Text	DBS	Time Stamp	Comments
72	627	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with imag\$3 with value\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:07	
73	773	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with imag\$3 with value\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:07	

Type	Hits	Search Text	DBs	Time Stamp	Comments
74	53	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with. (semiconductor\$1 or wafer\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with imag\$3 with value\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:08	
75	1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with charged with particle with beam with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	

Type	Hits	Search Text	DBs	Time Stamp	Comments
76	1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with parameter\$1 same charged with particle with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	
77	17	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with parameter\$1 and charged with particle with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	

Type	Hits	Search Text	DBs	Time Stamp	Comments
78	BRS 17	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with parameter\$1 and charged with particle with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	
79	BRS 1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with parameter\$1 and charged with particle with beam\$1 and relocat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:43	

Type	Hits	Search Text	DBS	Time Stamp	Comments
80	BRS 221	analy\$4 with (defect\$1 or error\$1 or malfunctions\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:23	
81	BRS 11	analy\$4 with (defect\$1 or error\$1 or malfunctions\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and SEM with chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:44	

Type	Hits	Search Text	DBs	Time Stamp	Comments
82	2	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and user\$1 with (interface\$1 or communication\$1) with defin\$3 with (condition\$1 or state\$1 or status\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	
83	1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and pause same user\$1 with (interface\$1 or communication\$1) with defin\$3 with (condition\$1 or state\$1 or status\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:31	

Type	Hits	Search Text	DBs	Time Stamp	Comments
84	1	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and pause same user\$1 with (interface\$1 or communication\$1) with defin\$3 with (condition\$1 or state\$1 or status\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	
85	65	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and pause with user\$1 with (interface\$1 or communication\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	

Type	Hits	Search Text	DBs	Time Stamp	Comments
86	1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and pause with user\$1 with (interfaces\$1 or communication\$1) and defin\$3 with (condition\$1 or state\$1 or status\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	
87	3	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and pause with user\$1 with (interfaces\$1 or communication\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 13:50	

Type	Hits	Search Text	DBs	Time Stamp	Comments
88	ISS&R 2	( "6539106" ) . PN.	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:59	
89	BRS 320	analy\$4 with ( defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductors\$1 or wafer\$1 or IC\$1 or (integrated adj circuits\$1) or chip\$1 or die\$1) and ion with beam\$1 with electron with beam\$1	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 13:51	
90	BRS 401	analy\$4 with ( defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductors\$1 or wafer\$1 or IC\$1 or (integrated adj circuits\$1) or chip\$1 or die\$1) and ion with beam\$1 with electr\$4 with beam\$1	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 13:51	

Type	Hits	Search Text	DBs	Time Stamp	Comments
91	BRS 5	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and ion with beam\$1 with mill\$3 with object\$1 and electr\$4 with beam\$1 with imag\$3 with object\$1	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:02	
92	BRS 1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and ion with beam\$1 with mill\$3 and electr\$4 with beam\$1 with imag\$3 and computer with execut\$3	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 14:04	

Type	Hits	Search Text	DBs	Time Stamp	Comments
93	BRS 5	analysis\$4 with (defects\$1 or errors\$1 or malfunction\$2 or problems\$1 or faults\$1 or fails\$3 or anomalies\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and ion with beam\$1 with mill\$3 and electr\$4 with beam\$1 with imag\$3 and computer and user\$1 with (interfaces\$1 or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 14:06	

Type	Hits	Search Text	DBs	Time Stamp	Comments
94	BRS 3	analys\$4 with (defect\$1 or errors\$1 or malfunctions\$2 or problems\$1 or faults\$1 or fail\$3 or anomalies\$3 or trouble\$1) with (semiconductor\$1 or wafers\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and ion with beam\$1 with mill\$3 and electr\$4 with beam\$1 with imag\$3 and computer and user\$1 with (interface\$1 or communicat\$3) and (delet\$3 or remov\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 14:06	

Type	Hits	Search Text	DBS	Time Stamp	Comments
		analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:03	
95	BRS 39	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:03	
96	BRS 13			2005/07/18 15:17	

Type	Hits	Search Text	DBS	Time Stamp	Comments
97 BRS 5		analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductors\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (Irelocat\$3 or locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:07	

Type	Hits	Search Text	DBs	Time Stamp	Comments
98	BRS 5	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (relocat\$3 or locat\$3 or re-locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:08	

Type	Hits	Search Text	DBs	Time Stamp	Comments
99	1	analysis\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (relocat\$3 or locat\$3 or re-locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with charged with beam\$1	US-PGPUB; JPO; DERWENT; IBM_TDB	2005/07/18 15:20	

Type	Hits	Search Text	DBS	Time Stamp	Comments
100	BRS 11	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with charged with beam\$1	US-PGPUB; USPAT; -EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:09	
101	BRS 1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with charged with beam\$1 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:09	

Type	Hits	Search Text	DBs	Time Stamp	Comments
102	BRS 2	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3). with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (adjust\$3 or calibrat\$3 or compensat\$3) with charged with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:17	

Type	Hits	Search Text	DBs	Time Stamp	Comments
103	BRS 2	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (adjust\$3 or calibrat\$3 or compensat\$3) with charg\$3 with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:17	

Type	Hits	Search Text	DBS	Time Stamp	Comments
104	BRS 5	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (relocat\$3 or locat\$3 or re-locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:21	

Type	Hits	Search Text	DBs	Time Stamp	Comments
105	BRS	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomai\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 with parameter\$1 and (relocat\$3 or locat\$3 or re-locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomai\$3 or trouble\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:22	

Type	Hits	Search Text	DBs	Time Stamp	Comments
106	BRS 5	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and (relocat\$3 or locat\$3 or re-locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:23	

Type	Hits	Search Text	DBs	Time Stamp	Comments
107	BRS 5	analy\$4 with (defect\$1 or errors\$1 or malfunctions\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafers\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and (relocat\$3 or locat\$3 or re-locat\$3) with (histor\$6 or previous\$2) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:24	

Type	Hits	Search Text	DBs	Time Stamp	Comments
108	BRS 5	analy\$4 with (defect\$1 or error\$1 or malfunctions\$2 or problem\$1 or fault\$1 or fail\$3 or anomals\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and (relocat\$3 or locat\$3 or re-locat\$3) with (histo\$6 or previous\$2) with imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:24	

Type	Hits	Search Text	DBs	Time Stamp	Comments
109	BRS 6	analy\$4 same (defect\$1 or errors\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafers\$1 or IC\$1 or integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and (relocat\$3 or locat\$3 or re-locat\$3) with (histo\$6 or previous\$2) with imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:26	

Type	Hits	Search Text	DBs	Time Stamp	Comments
110	BRS 1	analy\$4 same (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomals\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charged with beam\$1 and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and (relocat\$3 or locat\$3 or re-locat\$3) with (histo\$6 or previous\$2) with imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:27	

Type	Hits	Search Text	DBs	Time Stamp	Comments
111	6	analy\$4 same (defect\$1 or errors\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafers\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charged with beam\$1 and control\$5 with stage\$1 with receiv\$3 with (position\$3 or locat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:48	
112	2	analy\$4 same (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomalous\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charged with beam\$1 and control\$5 with stage\$1 with receiv\$3 with (position\$3 or locat\$4) with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:48	

Type	Hits	Search Text	DBs	Time Stamp	Comments
113	BRS 17	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomals\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 with (two or dual)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 16:41	
114	BRS 1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomals\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 with (two or dual) and path\$1 with travel\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 16:43	

Type	Hits	Search Text	DBs	Time Stamp	Comments
115	BRS	807 702/183.cc1s.	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/18 17:15	
116	BRS	2102 702/117,118,183,185.cc1s.	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/18 17:16	